

Title (en)
PANE WITH ELECTRIC CONNECTION ELEMENT AND CONNECTING ELEMENT ATTACHED THERETO

Title (de)
SCHEIBE MIT ELEKTRISCHEM ANSCHLUSSELEMENT UND DARAN ANGEBRACHTEM VERBINDUNGSELEMENT

Title (fr)
DISQUE DOTÉ D'UN ÉLÉMENT DE RACCORDEMENT ÉLECTRIQUE ET ÉLÉMENT DE LIAISON DISPOSÉ DESSUS

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Application
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Abstract (en)
[origin: WO2016177653A1] The invention relates to a wafer having at least one electric connection element, at least comprising: a substrate (1), an electrically conductive structure (2) on an area of the substrate (1), a bridge-like electric connection element (3), comprising a bridge area (3a) and at least two soldering legs (3b), which are connected by a soldering material (4) to an area of the electrically conductive structure (2), and an electric connecting element (5) fitted to the connection element (3), wherein the connecting element (5) is fitted to the surface (I) of the bridge area (3a) that faces the substrate (1) or is fitted to the surface (II) of the bridge area (3a) that faces away from the substrate (1) and is led around the bridge area (3a), such that the connecting element rests on the surface (I) of the bridge area (3a) that faces the substrate (1), wherein the difference between the melting temperature of the material of the connection element (3) and the melting temperature of the material of the connecting element (5) is greater than 200 °C, and wherein the connecting element (5) is fitted to the connection element (3) by means of a welded connection.

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